

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Nam-Yong OH	08/19/2010
Seong-Chan HAN	08/19/2010
Jae-Young KIM	08/19/2010
Jae-Hoon CHOI	08/19/2010
RECEIVING PARTY DATA	
Name:	Samsung Electronics Co., Ltd
Street Address:	416 Maetan-dong, Yeongtong-gu
City:	Suwon-si, Gyeonggi-do
State/Country:	REPUBLIC OF KOREA
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12881439
CORRESPONDENCE DATA	
Fax Number:	(202)775-1901
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	202-775-1900
Email:	patent@snkiplaw.com
Correspondent Name:	STANZIONE & KIM, LLP
Address Line 1:	919 18TH STREET, N.W.
Address Line 2:	SUITE 440
Address Line 4:	WASHINGTON, DISTRICT OF COLUMBIA 20006
ATTORNEY DOCKET NUMBER:	207-1038
NAME OF SUBMITTER:	Seungman Kim
Total Attachments: 1 source=Assignment#page 1.tif	

CH \$40.00 12881439

501289701

PATENT
REEL: 024983 FRAME: 0614

U.S. ASSIGNMENT

IN CONSIDERATION of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned inventor(s) (hereinafter, "ASSIGNOR") by (insert Name(s) & Address(es) of ASSIGNEE(S))

SAMSUNG Electronics Co., Ltd.
416 Maetan-dong, Yeongtong-gu
Suwon-si, Gyeonggi-do
Republic of Korea

(hereinafter, "ASSIGNEE"), the receipt of which is hereby acknowledged, the undersigned ASSIGNOR hereby sells, assigns and transfers to ASSIGNEE the entire and exclusive right, title and interest to the invention entitled

METHOD OF ATTACHING A SOLDER BALL AND METHOD OF REPAIRING A MEMORY MODULE

relating to International Patent Application PCT _____/_____ and/or for which application for Letters Patent of the United States was executed on even date herewith or, if not so executed, was:

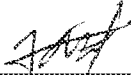


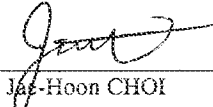
- (a) executed on _____; (Insert date of execution of application, if not concurrent)
- (b) filed on _____

Serial No. _____/_____; *** Any registered attorney of Stanzione & Kim, LLP, 919 18th Street, N.W., Washington, D.C. 20006, is hereby authorized to insert in section (b) above the specified data, when known.***

and to said application and all Letters patent(s) of the United States granted on said application and any continuation, division, renewal, substitute, reissue or reexamination application based thereon, for the full term or terms for which the said Letters Patent(s) may be granted and including any extensions thereof (collectively, hereinafter, "said application(s) and Letters Patent(s)").

The ASSIGNOR agree(s), when requested by said ASSIGNEE and without charge to but at the expense of said ASSIGNEE, to do all acts which the ASSIGNEE may deem necessary, desirable or expedient, for securing, maintaining and enforcing protection for said invention, including in the preparation and prosecution of said application(s) and the issuance of said Letters Patent(s), in any interference, reissue, reexamination, or public use proceeding, and in any litigation or other legal proceeding which may arise or be declared in relation to same, such acts to include but not be limited to executing all papers, including separate assignments and declarations, taking all rightful oaths, providing sworn testimony, and obtaining and producing evidence.

IN WITNESS WHEREOF, the undersigned inventor(s) has (have) affixed his/her/their signature(s).

- | (Typed Name & Signature of Inventor(s)) | (Date) |
|--|--------------|
| 1) 
Nam-Yong OH | 2010. 08. 19 |
| 2) 
Seong-Chan HAN | 2010. 08. 19 |
| 3) 
Jae-Young KIM | 2010. 08. 19 |
| 4) 
Jae-Hoon CHOI | 2010. 08. 19 |

